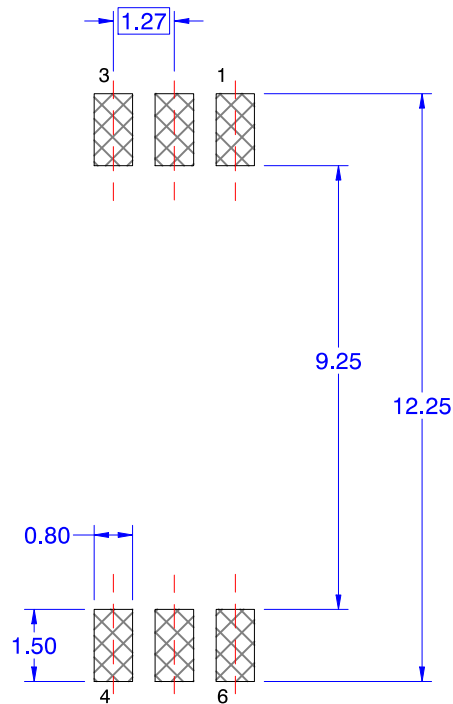
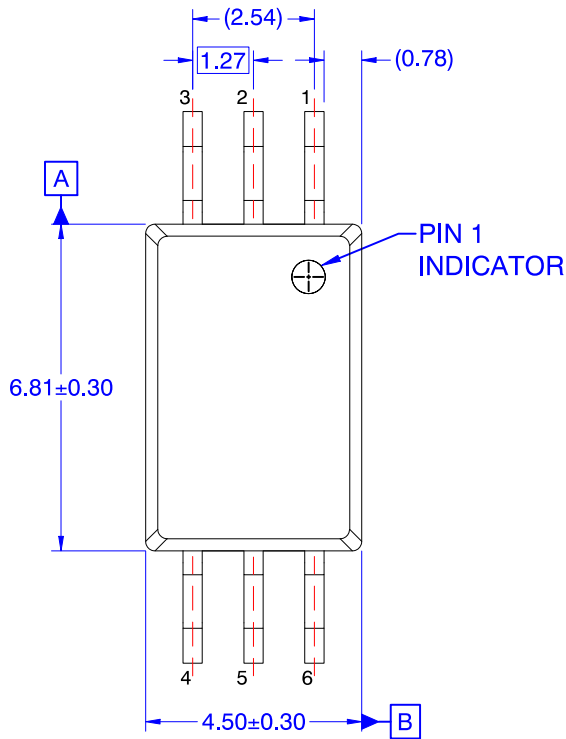
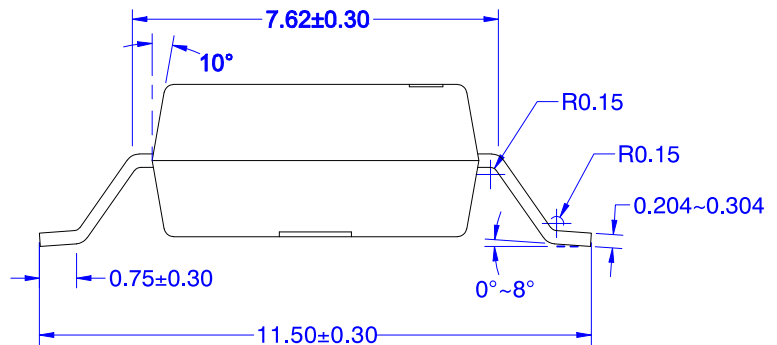
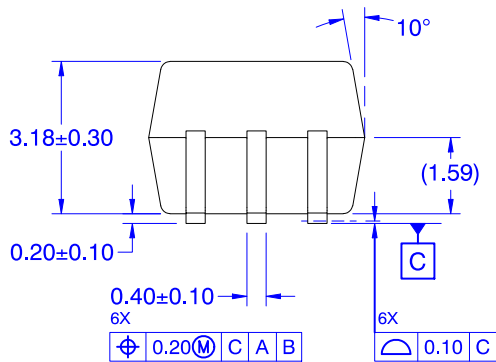


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CASE 751EM
ISSUE O

DATE 30 SEP 2016



RECOMMENDED LAND PATTERN



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) NO STANDARD APPLIES TO THIS PACKAGE
 - B) ALL DIMENSIONS ARE IN MILLIMETERS.
 - C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH, AND TIE BAR EXTRUSION.
 - D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.

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